



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA7P120-1U1M	812Q*6TAN06B	A	Z6HA	2016-09-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	2.40	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	1 - 1.6 - 0.6	2	No lead	
Comment	Package: DFN.16.10.06-105-2L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	812Q*6TAN06B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.156	mg	supplier	die	Silicon (Si)	7440-21-3		0.101	mg	647436	42083
				supplier	metallization	Aluminium (Al)	7429-90-5		0.047	mg	301282	19583
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	25641	1667
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	6410	417
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.003	mg	19231	1250
Leadframe	Copper and its alloy	0.721	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.677	mg	938974	282083
				supplier	alloy	Nickel (Ni)	7440-02-0		0.025	mg	34674	10417
				supplier	alloy	Silicon (Si)	7440-21-3		0.004	mg	5548	1667
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.001	mg	1387	417
				supplier	alloy	Iron (Fe)	7439-89-6		0.001	mg	1387	417
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	5547	1667
				supplier	metallization	Nickel (Ni)	7440-02-0		0.008	mg	11096	3333
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	1387	417
Die attach	Other organic materials	0.033	mg	supplier	glue	Silver (Ag)	7440-22-4		0.025	mg	757576	10417
				supplier	glue	Butyl diethylene glycol acetate	124-17-4		0.003	mg	90909	1250
				supplier	glue	Bismaleimide resin	35325-39-4		0.002	mg	60606	831
				supplier	glue	High boiling methacrylate	Proprietary		0.001	mg	30303	417
				supplier	glue	Acrylic monomer	Proprietary		0.001	mg	30303	417
Bonding wire	Other inorganic materials	0.022	mg	supplier	glue	Acrylate	Proprietary		0.001	mg	30303	417
				supplier	bonding wire	Copper (Cu)	7440-50-8		0.022	mg	1000000	9167
Encapsulation	Other inorganic materials	1.468	mg	supplier	molding compound	Silica Fused	60676-86-0		1.376	mg	937330	573333
				supplier	molding compound	Epoxy Resin	25068-38-6		0.044	mg	29973	18333
				supplier	molding compound	Phenol Resin	29690-82-2		0.044	mg	29973	18333
				supplier	molding compound	Carbon Black	1333-86-4		0.004	mg	2724	1667